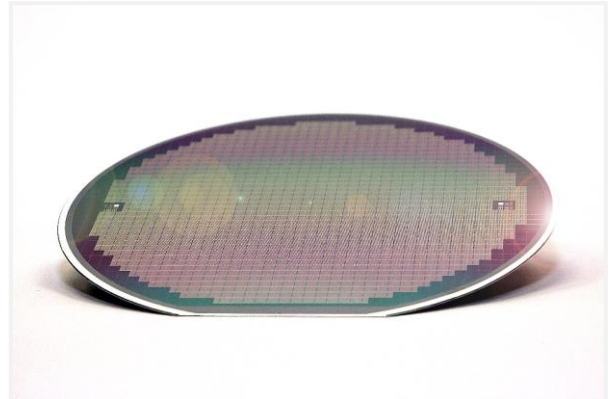


## Description

The NT16-3K Thermal Test Chip is designed as a modular system to provide the maximum of flexibility for thermal characterization and qualification of materials, packages and systems.

The smallest full functional chip cell of 3.2 mm x 3.2 mm consists of 10 heating resistors, which provide uniform heating and a resistor temperature sensor in the center. Heaters as well as temperature sensor are fabricated using only one Titanium layer as adhesion and barrier layer.

The chip can be used in any desired matrix, such as square or rectangular. All temperature sensors, whether in a single cell or arrayed cell configuration, can be individually addressed, allowing localized temperature measurements. The heating resistors on each chip cell can be powered individually in a serial or parallel configuration to achieve customers and applications specific electrical resistance values and heat dissipations.



## Technical Specification

### Technology and Methodology

Fabrication technology	Thin Film
Assembly technology	Wirebond technology
Sensor	Resistance thermometer

### Wafer

Wafer material	Silicon with glass passivation	
Wafer size	150	mm
	6	inch
Wafer thickness	400	µm
Cell size	3.2 x 3.2	mm <sup>2</sup>
Scribe line between cells	100	µm
Matrix	up to 20 x 20 cells (66 x 66 mm <sup>2</sup> )	
Backside metallization	Ti/Pt/Au	
Backside metal thickness	100/100/100	nm

### Heater

Heater type	resistor	
Resistors per chip	10	
Resistance per resistor	160	Ω
Max current per heater line	400	mA
Max power per cell	250 *	W
Active heater area	> 62% of cell area	
Maximum temperature	350 **	°C

### Sensor

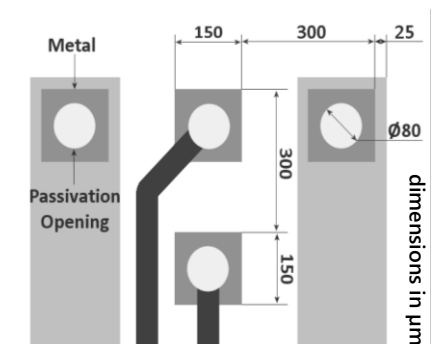
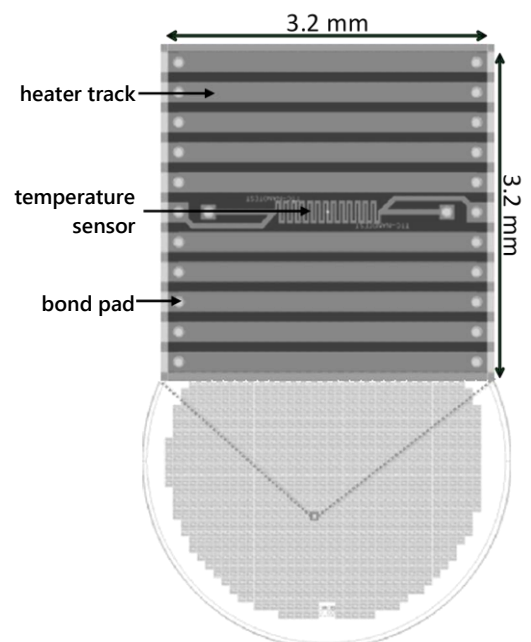
Sensor type	meander-structured resistor	
Sensor position	cell center	
Sensing method	four-terminal sensing	
Resistance value	3	kΩ
	8	Ω/K
Sensitivity	8 mV/K @ 1mA	
Lateral size	870	µm

### Assembly

Assembly technology	Wirebond technology	
Solder bump metallization	Al	
Pad size	150	µm
Pad raster	300	µm

\* high power dissipation is only possible to achieve with proper cooling

\*\* 350°C operating temperature only applies to the chip itself. A much lower maximum operating temperature is likely due to other assembly components (i.e. PCB and solder) and has to be regarded.



## Chip selection guide

You can calculate the length of the chip edge depending on the number of cells per row / column using the following formula.

$$\text{edge length} = n \times \text{cellLength} + (n-1) \times \text{scribeLineLength}$$

$$\text{edge length} = n \times 3.2 \text{ mm} + (n-1) \times 0.1 \text{ mm}$$

### Example: (3 x 3 matrix of cells)

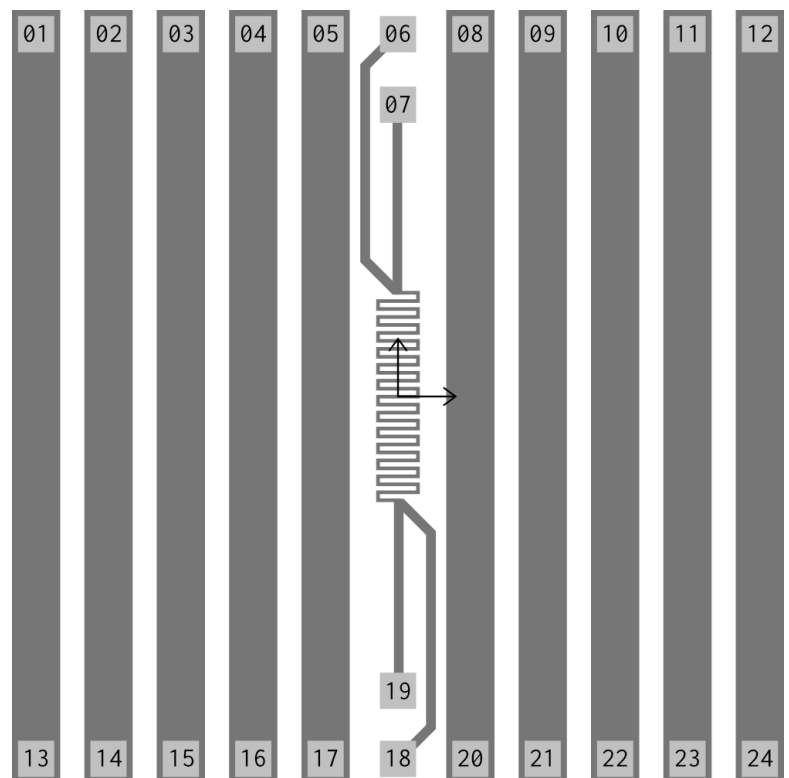
$$\text{edge length} = 3 \times 3.2 \text{ mm} + (3-1) \times 0.1 \text{ mm}$$

$$\text{chip size} = 9.8 \times 9.8 \text{ mm}^2$$

## Pin configuration

For absolute coordinates of each pin the point of origin (X=0, Y=0) is the cell center. Nomenclature of pins is involving a prefixed letter which indicates the purpose of the specific pin. Hx pins for connection to heating structures, pins SI for sensing current input and SV pins for voltage sensing.

#	Name	X [μm]	Y [μm]
01	H1	-1500	1500
02	H2	-1200	1500
03	H3	-900	1500
04	H4	-600	1500
05	H5	-300	1500
06	SI	0	1500
07	SV	0	1200
08	H6	300	1500
09	H7	600	1500
10	H8	900	1500
11	H9	1200	1500
12	H10	1500	1500
13	H1	-1500	-1500
14	H2	-1200	-1500
15	H3	-900	-1500
16	H4	-600	-1500
17	H5	-300	-1500
18	SI	0	-1500
19	SV	0	-1200
20	H6	300	-1500
21	H7	600	-1500
22	H8	900	-1500
23	H9	1200	-1500
24	H10	1500	-1500



## Application remarks

All offered dies are supposed to be used for characterization purposes. The application of the data from the test die to a functional system lies in the responsibility of the user. Nanotest makes no warranty, express or implied including the implied warranties of merchantability and fitness for a particular purpose, that the user's system designed using that data will perform as intended.